AMENDMENTS TO THE CLAIMS

This listing of the claims replaces any and all prior versions and listings of claims in the application:

LISTING OF THE CLAIMS

1. (Presently amended) A slider assembly comprising a plurality of sliders for a data storage system bonded by a debondable solid encapsulant, wherein the encapsulant is comprised of a blend of styrene and butadiene polymers, of a weight ratio of about 19:1 to about 17:3, or about 9:1, or about 10% polybutadiene, wherein at least some sliders have encapsulant-free surfaces[[,]] which are coplanar to each other.

2 (Original): The slider assembly of claim 1, having a contiguous planar surface comprised of at least one encapsulant region and containing the coplanar slider surfaces.

3 (Original): The slider assembly of claim 2, wherein the sliders are arranged in an array.

4 (Original): The slider assembly of claim 3, wherein the array is a rectilinear array.

5 (Original): The slider assembly of claim 4, wherein the sliders do not contact each other.

6 (Original): The slider assembly of claim 4, wherein the coplanar surfaces of the sliders are each an air-bearing surface.

7 (Original): The slider assembly of claim 6, further comprising a substrate in contact with the air-bearing surfaces.

8 (Original): The slider assembly of claim 7, wherein the substrate is comprised of a laminate of a flexible tape and an adhesive, wherein the adhesive is in contact with the air-bearing surfaces.

9 (Original): The slider assembly of claim 8, wherein the adhesive is a pressure sensitive adhesive.

10 (Original): The slider assembly of claim 8, wherein the adhesive preferentially adheres to the tape over the air-bearing surfaces.

11 (Original): The slider assembly of claim 4, wherein the encapsulant does not substantially outgas under vacuum.

12 (Original): The slider assembly of claim 4, further comprising a carrier attached to the encapsulant and/or at least one slider, wherein the carrier does not cover any of the coplanar slider surfaces.

13 (Original): The slider assembly of claim 6, further comprising a resist layer on the air-bearing surfaces, wherein the encapsulant is mechanically stable upon exposure to the resist layer or any component thereof.

14 (Original): The slider assembly of claim 13, wherein the encapsulant is subject to solvation by a solvent not found in the resist layer.

15-18 (Cancelled)

19 (Original): The slider assembly of claim 4, wherein the styrene and butadiene polymers are present is a weight ratio of about 19:1 to about 17:3.

20 (Original): The slider assembly of claim 19, wherein the styrene and butadiene polymers are present in a weight ratio of about 9:1.

21-30 (Cancelled).

31. (Previously presented) The slider assembly of claim 1, wherein the encapsulant blend provides markedly improved performance, with improved toughness and filling characteristics.